



REV	MODIFICATION	DATE	DRAW
A0	Release To Production	2010.10.19	Ivy
A1	Release To ECN20120505	2012.05.11	Seven
A2	Release To ECN20150603	2015.06.09	Michelle

**RoHS Compliant**

**Specification**  
 1.Current Rating:2.5A AC/DC  
 2.Voltage Rating:250V AC/DC  
 3.Contact Resistance:20mΩ Max.  
 4.Insulation Resistance:1000MΩ Min. At DC 500V  
 5.Dielectric Withstanding Voltage:AC1000V/Minute  
 6.Operating Temperature:-25°C~+85°C

**Material:**  
 1.Housing:High Temperature Thermoplastic UL94V-2  
 2.Contact Pin:Copper Alloy SQ. Pin 0.64mm

**Finish:**  
 1.Housing:Red  
 2.Contact Pin:Bright Tin Over Nickel

Part No.: ADO3614 03 0 1 5 2

No. Of Pin: 03  
 Packing: 5:Bag

Housing Material: 0:PA66 UL94V-2 Red  
 Plating: 1:Bright Tin Plated Over Nickel



TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.	TITLE: Wire To Board Wafer 2.54mm 180° 3P DIP Short Back Board		
.x± 0.35	x.± 2'	APR. C.F.Liao 20150609	PART NO. AD03614030152	DWG NO. AD03614030152	
.xx± 0.25	.x'± 1'	CHK. Abel 20150609	UNITS: mm	CUSTOMER DRAWING	
.xxx± 0.15	.xx'± 0.5'	DRA. Michelle 20150609	SIZE: A4	SCALE 4:1	SHEET 1 / 1
			REV A2	V	

**RECOMMENDED P.C.B LAYOUT**